

METHOD FOR FABRICATING MULTI-LAYERED PCB

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Abstract of KR 20030080546 (A)

PURPOSE: A method for fabricating a multi-layered PCB(Printed Circuit Board) is provided to remove a post-process and simplify a total process by performing a preprocess for a core member by means of a stiffening agent. **CONSTITUTION:** A stiffening agent is coated on a surface of a copper substrate to form the surface roughness and an organic layer. A pattern etching process is performed on the surface of the copper substrate including the surface roughness and the organic layer. The first cleaning process is performed to remove alien substances from the surface of the copper substrate. The second cleaning process is performed to remove the acid solution from the surface of the copper substrate. A dry process is performed to remove the moisture from the surface of the copper substrate. A stacking process is performed to adhere substrates to each other.

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